

Title (en)  
Device for high pressure forming

Title (de)  
Vorrichtung zum Innenhochdruckumformen

Title (fr)  
Dispositif pour le formage à haute pression

Publication  
**EP 0665072 B1 19981209 (DE)**

Application  
**EP 94113101 A 19940823**

Priority  
DE 4402674 A 19940129

Abstract (en)  
[origin: US5570602A] In an apparatus for molding particularly a tubular blank (1) of a ductile metal with internal high pressure in a mold, which has a cavity (5), a lower part (2) and a removable upper part (3) as well as a mechanism (6, 7, 13-21) for holding the upper (3) and lower parts (2) together, this mechanism consists of a pot (7), which is provided with a lid (15) and in which the mold (2, 3) is inserted. Between the pot (7) and the lid (15), a bayonet lock (13-20) is provided with a row of interlocking devices (14, 19), which can be brought into and out of engagement by means of a ring (16), which can be rotated relative to the mold (2, 3), and with an annular (9; 21) introduction of force into the lower part (2) and the upper part (3) near their circumference. Said ring (16) is disposed at a lid (6), which is mounted on the upper part (3) of the mold and can be rotated by means of a hydraulic cylinder (17) acting with a tangential force component between the remaining lid (15) and the ring (16) over oscillating cranks (18) hinged at the remaining lid (15) and the ring (16) with approximately radial extent.

IPC 1-7  
**B21D 26/02**

IPC 8 full level  
**B21D 39/08** (2006.01); **B21D 26/02** (2011.01); **B21D 26/039** (2011.01); **B21D 26/047** (2011.01)

CPC (source: EP US)  
**B21D 26/039** (2013.01 - EP US); **B21D 26/047** (2013.01 - EP US)

Cited by  
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**US 5570602 A 19961105**; AT E174236 T1 19981215; DE 4402674 A1 19950803; DE 59407444 D1 19990121; EP 0665072 A1 19950802; EP 0665072 B1 19981209; JP 3709894 B2 20051026; JP H07214187 A 19950815

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**US 37548695 A 19950119**; AT 94113101 T 19940823; DE 4402674 A 19940129; DE 59407444 T 19940823; EP 94113101 A 19940823; JP 28237394 A 19941012